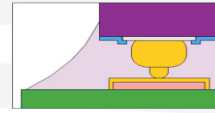


TWO ASSEMBLY TECHNOLOGIES FOR HIGH DENSITY CIRCUITS MINIATURISATION.



ICA

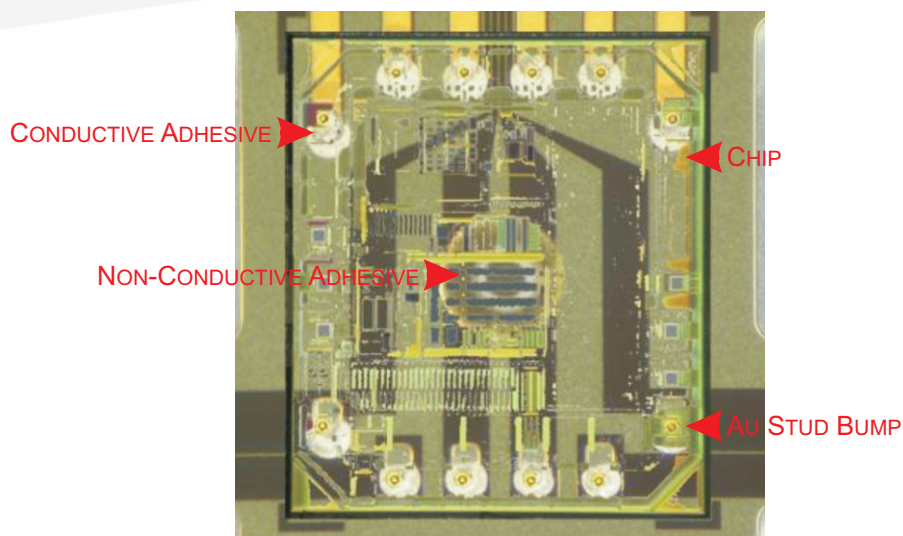
ISOTROPICALLY CONDUCTIVE ADHESIVE (+UNDERFILL)



NCP

NON-CONDUCTIVE PASTE

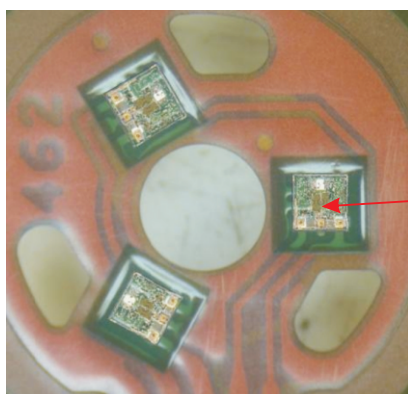
ICA / ISOTROPICALLY CONDUCTIVE ADHESIVE



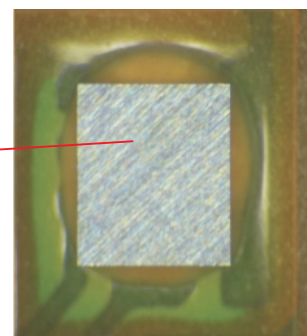
TRANSPARENCY

HYBRID SA IS ABLE TO PERFORM FLIP-CHIP ASSEMBLY ON ELECTRONIC MODULES ACCORDING TO SPECIFICATIONS DEFINED IN COLLABORATION WITH THE CLIENT. FOR A GOOD MANUFACTURING, IT IS IMPORTANT TO TEAM UP, ESPECIALLY FOR THE LAYOUT DESIGN. A FLIP-CHIP ASSEMBLY ALLOWS OUR CLIENTS TO INCREASE MINIATURIZATION OF THEIR MODULE BY REDUCING COMPONENTS CONGESTION TO AN ABSOLUTE MINIMUM.

NCP / NON-CONDUCTIVE PASTE



TRANSPARENCY



NON-CONDUCTIVE PASTE AFTER THERMOCOMPRESSION